

Product Description

EVSF100 1.5 W/mK silicone-based thermal pads are used for filling the two contact surfaces. They are ultra-soft and have good resilience, so effectively exclude air from the contact interface. The products are naturally tacky, can be die-cut into various shapes, easy to operate.

Product Illustration



Features and Benefits

- High Thermal Conductivity
- Excellent Flame Retardant
- Good Flexibility and Resilience

Applications

- CPU/GPU Chips
- Control Boards
- Memory/Graphics Memory Particles

(Standard sheet size 200mm x 300mm. Material may be cut per customer drawing.)

| Properties | Unit | Value | Test Method |
|---------------------------------|-----------------------|------------|-------------|
| Color | - | White | Visual |
| Thermal Conductivity | W/mK | 1.5 | ASTM D5470 |
| Thermal Impedance (1mm, @30psi) | °C*in ² /W | 0.90 | ASTM D5470 |
| Thickness | mm | 0.3 – 10.0 | ASTM D374 |
| Tensile Strength | psi | 40 | ASTM D412 |
| Standard Hardness | Shore 00 | 40/60 | ASTM D2240 |
| Elongation | % | 50 | ASTM D412 |
| Density | g/cm ³ | 2.2 | ASTM D792 |
| Dielectric Strength (@AC) | kV/mm | > 8 | ASTM D149 |
| Operating Temp. | °C | -50 - 200 | - |
| Flame Rating | - | V-0 | UL94 |
| RoHS | - | PASS | IEC 62321 |
| Halogen | - | PASS | EN 14582 |
| REACH | - | PASS | EN 14372 |

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

Product Specifications: According to Customers' Requirements

Storage & Transportation: Store in a well-ventilated, cool, and dry place, away from open flames. This product is non-toxic and should be stored and transported as a non-hazardous material.

Packaging: Customized packaging according to customer requirements.

Shelf Life: 24 months